

Date Created : 2007/08/17
Date Issued On : 2007/09/07
PCN# : Q3073305

FORECAST CHANGE NOTIFICATION

This is to inform you that a design and/or process change will be made to the following product(s). This notification is for your information and concurrence. This is a preliminary notification. A Final PCN will be issued when qualification is complete and data is available.

If you require data or samples to qualify this change, please contact **Fairchild Semiconductor within 30 days of receipt of this notification.**

If you have any questions concerning this change, please contact:

Technical Contact:

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PCN Originator:

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Implementation of change:

Expected 1st Device Shipment Date: 2007/11/27

Earliest Year/Work Week of Changed Product: 0748

Change Type Description: New Assembly Site Location/Qualification

Description of Change (From): Current wafer and die sales Assembly Site: STATSChipPAC MALAYSIA SDN BHD (SCM) at 73, Lorong Enggang ulu Kelang FTZ, 54200 Kuala Lumpur, Malaysia.

Description of Change (To): New wafer and die sales Assembly Site: FAIRCHILD SEMICONDUCTOR (PHILIPPINES), INC. (FSCP) at MEPZ, Lapu-lapu City, Cebu Philippines 6015.

Reason for Change : Assembly Site Transfer from SCM to FSCP due to closure of the SCM Power Division handling the wafer and die sale requirements of Fairchild Semiconductor.

Qual/REL Plan Numbers : Q20070314

Qualification :

In-sourcing qualification for Wafer and Die Sales.

Qualification Stress Test and Sample Size Detail

Device #1	PCF75337W_S2496				
Package:	-1				
#Leads:	-1				
				Readpoints	Samples
Stress	P/C	Standard	Conditions		

Device #2	PCGA3056W			Readpoints	Samples
Package:	-1				
#Leads:	-1				
Stress	P/C	Standard	Conditions		

Device #3	PCRU420D_R4707			Readpoints	Samples
Package:	-1				
#Leads:	-1				
Stress	P/C	Standard	Conditions		

Device #4	PCRU420D_R4707S			Readpoints	Samples
Package:	-1				
#Leads:	-1				
Stress	P/C	Standard	Conditions		

Device #5	PCRU860D_R4926			Readpoints	Samples
Package:	-1				
#Leads:	-1				
Stress	P/C	Standard	Conditions		

Product Id Description : This change will affect Fairchild's Wafer and Die sales business currently assembled in STATSChipPAC Malaysia. The devices affected by this change are listed in the "Affected FSIDs" section.

Affected FSIDs :

ISL9R1560W2_R4800	ISL9R18120W2	ISL9R30120W2
ISL9R860W2	PCF033AN08ZW_R4800	PCF045AN08W_R4800
PCF10AN06W	PCF2532W_R4800	PCF25N05W
PCF27N50W	PCF3632W_R4800	PCF40N10W
PCF70N06W	PCF75307W_R4903	PCF75337W_S2496
PCF75339W	PCF75545W_R4800	PCF75639W_R4799
PCF75639W_R4903	PCF75652W	PCF75652W_R4800
PCF75852W	PCF75852W_R4800	PCF76443W
PCFA75545W	PCFA75652W	PCG12N60A4W_R4800
PCG12N60C3W	PCG20N60A4W_R4800	PCG20N60C3W
PCG2N120CNW_R4800	PCG30N60A4W_R4800	PCG30N6W
PCG40N60A4W_R4800	PCG40N6W	PCGA3056W
PCRH1260W	PCRH1560W	PCRH3060F
PCRH75120W_R4800	PCRU1520W	PCRU420D_R4707
PCRU420D_R4707S	PCRU8060W	PCRU8100W
PCRU860D_R4926		